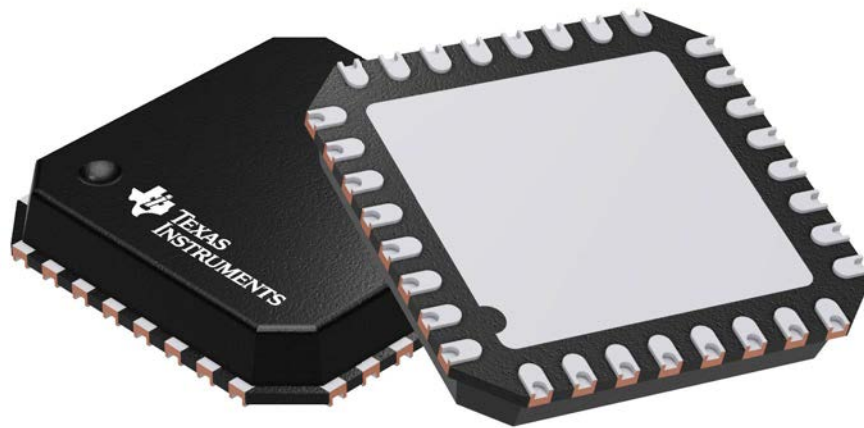


## GENERIC PACKAGE VIEW

RHM 32

VQFN - 0.9 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



Images above are just a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.

4205347/C

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